



July 10, 2008

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/796,427 Mar. 9, 2004

MOU-SHIUNG LIN et al.

"WIREBOND PAD FOR SEMICONDUCTOR CHIP
OR WAFER"

Grp. Art Unit: 2822

LEWIS, MONICA

RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Final Office Action mailed Jun. 11, 2008, please amend the above-identified application for patent and consider the remarks as follows:

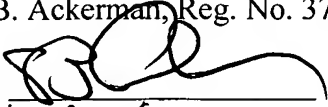
CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Jul. 29, 2008.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date


July 29, 2008

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims begin on page 4 of this paper.

Amendments to the Drawings begin on page 10 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 11 of this paper.

An Appendix including replacement figures is attached following page 19 of this paper.